



Material Content Data Sheet



Sales Product Name	TLE9873QXW40			Issued	1. August 2018			
MA#	MA001583696							
Package	PG-VQFN-48-29			Weight*	130.25 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.821	3.70	3.70	37011	37011
leadframe	inorganic material	phosphorus	7723-14-0	0.018	0.01		138	
	non noble metal	zinc	7440-66-6	0.072	0.06		550	
	non noble metal	iron	7439-89-6	1.433	1.10		11003	
wire	non noble metal	copper	7440-50-8	58.193	44.69	45.86	446772	458463
	noble metal	gold	7440-57-5	0.858	0.66	0.66	6590	6590
encapsulation	organic material	carbon black	1333-86-4	0.181	0.14		1392	
	plastics	epoxy resin	-	7.675	5.89		58921	
	inorganic material	silicondioxide	60676-86-0	52.574	40.36	46.39	403634	463947
leadfinish	non noble metal	tin	7440-31-5	2.596	1.99	1.99	19934	19934
plating	noble metal	silver	7440-22-4	0.614	0.47	0.47	4713	4713
glue	plastics	epoxy resin	-	0.280	0.21		2149	
	noble metal	silver	7440-22-4	0.937	0.72	0.93	7193	9342
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com